

20-BIT FET BUS SWITCH

2.5-V/3.3-V LOW-VOLTAGE BUS SWITCH WITH 5-V-TOLERANT LEVEL SHIFTER

Check for Samples: [SN74CB3T16210-Q1](#)

FEATURES

- Qualified for Automotive Applications
- Member of the Texas Instruments Widebus™ Family
- Output Voltage Translation Tracks V_{CC}
- Supports Mixed-Mode Signal Operation on All Data I/O Ports
 - 5-V Input Down to 3.3-V Output Level Shift With 3.3-V V_{CC}
 - 5-V/3.3-V Input Down to 2.5-V Output Level Shift With 2.5-V V_{CC}
- 5-V-Tolerant I/Os With Device Powered Up or Powered Down
- Bidirectional Data Flow With Near-Zero Propagation Delay
- Low ON-State Resistance (r_{on}) Characteristics ($r_{on} = 5\ \Omega$ Typ)
- Low Input/Output Capacitance Minimizes Loading ($C_{io(OFF)} = 5\text{ pF}$ Typ)
- Data and Control Inputs Provide Undershoot Clamp Diodes
- Low Power Consumption ($I_{CC} = 40\ \mu\text{A}$ Max)
- V_{CC} Operating Range From 2.3 V to 3.6 V
- Data I/Os Support 0- to 5-V Signaling Levels (0.8 V, 1.2 V, 1.5 V, 1.8 V, 2.5 V, 3.3 V, 5 V)
- Control Inputs Can Be Driven by TTL or 5-V/3.3-V CMOS Outputs
- I_{off} Supports Partial-Power-Down Mode Operation

- Supports Digital Applications: Level Translation, PCI Interface, USB Interface, Memory Interleaving, and Bus Isolation
- Ideal for Low-Power Portable Equipment

**DGG PACKAGE
(TOP VIEW)**

NC	1	48	1OE
1A1	2	47	2OE
1A2	3	46	1B1
1A3	4	45	1B2
1A4	5	44	1B3
1A5	6	43	1B4
1A6	7	42	1B5
GND	8	41	GND
1A7	9	40	1B6
1A8	10	39	1B7
1A9	11	38	1B8
1A10	12	37	1B9
2A1	13	36	1B10
2A2	14	35	2B1
V_{CC}	15	34	2B2
2A3	16	33	2B3
GND	17	32	GND
2A4	18	31	2B4
2A5	19	30	2B5
2A6	20	29	2B6
2A7	21	28	2B7
2A8	22	27	2B8
2A9	23	26	2B9
2A10	24	25	2B10

NC - No internal connection

DESCRIPTION/ORDERING INFORMATION

The SN74CB3T16210-Q1 is a high-speed TTL-compatible FET bus switch with low ON-state resistance (r_{on}), allowing for minimal propagation delay. The device fully supports mixed-mode signal operation on all data I/O ports by providing voltage translation that tracks V_{CC} . The SN74CB3T16210-Q1 supports systems using 5-V TTL, 3.3-V LVTTTL, and 2.5-V CMOS switching standards, as well as user-defined switching levels (see [Figure 1](#)).



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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

DESCRIPTION/ORDERING INFORMATION (CONTINUED)

The SN74CB3T16210-Q1 is organized as two 10-bit bus switches with separate output-enable ($\overline{1OE}$, $\overline{2OE}$) inputs. It can be used as two 10-bit bus switches or as one 20-bit bus switch. When \overline{OE} is low, the associated 10-bit bus switch is ON, and the A port is connected to the B port, allowing bidirectional data flow between ports. When \overline{OE} is high, the associated 10-bit bus switch is OFF, and a high-impedance state exists between the A and B ports.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} feature ensures that damaging current will not backflow through the device when it is powered down. The device has isolation during power off.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

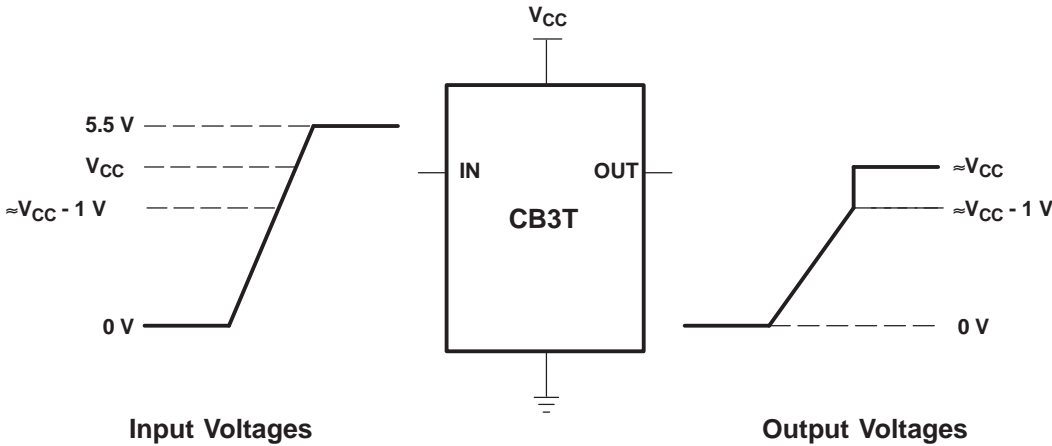
ORDERING INFORMATION

T_A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	TSSOP – DGG	Reel of 2000	CCB3T16210QDGGRQ1	CB3T16210Q

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE
(EACH 10-BIT BUS SWITCH)

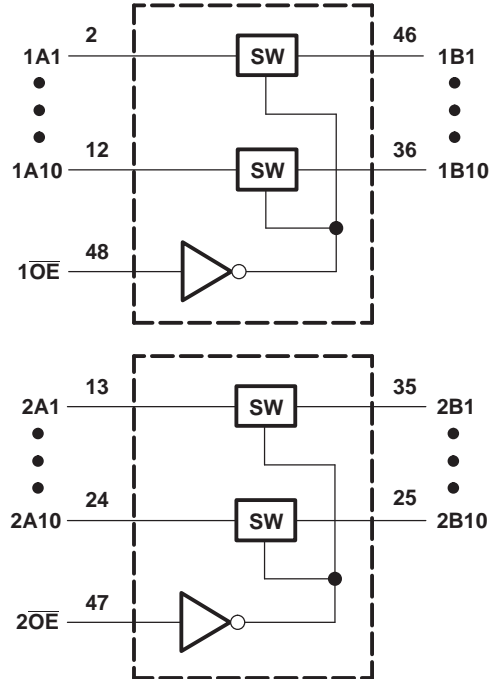
INPUT \overline{OE}	INPUT/OUTPUT A	FUNCTION
L	B	A port = B port
H	Z	Disconnect



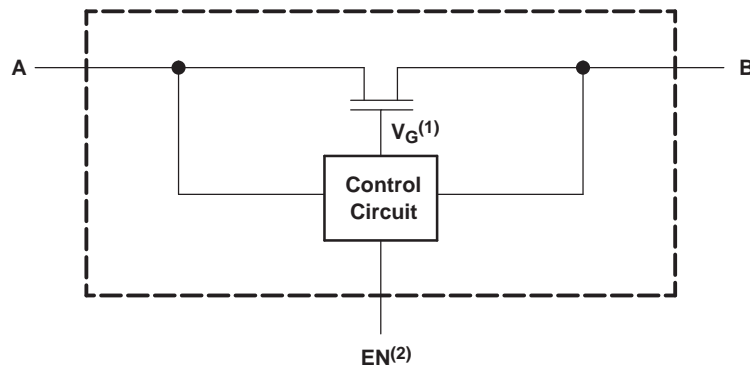
If the input high voltage (V_{IH}) level is greater than or equal to $V_{CC} - 1\text{ V}$, and less than or equal to 5.5 V, the output high voltage (V_{OH}) level will be equal to approximately the V_{CC} voltage level.

Figure 1. Typical DC Voltage Translation Characteristics

LOGIC DIAGRAM (POSITIVE LOGIC)



SIMPLIFIED SCHEMATIC, EACH FET SWITCH (SW)



- (1) Gate voltage (V_G) is equal to approximately $V_{CC} + V_T$ when the switch is ON and $V_I > V_{CC} + V_T$.
 (2) EN is the internal enable signal applied to the switch.

Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		-0.5	7	V
V_{IN}	Control input voltage range ^{(2) (3)}		-0.5	7	V
$V_{I/O}$	Switch I/O voltage range ^{(2) (3) (4)}		-0.5	7	V
I_{IK}	Control input clamp current	$V_{IN} < 0$		-50	mA
$I_{I/OK}$	I/O port clamp current	$V_{I/O} < 0$		-50	mA
I_{IO}	ON-state switch current ⁽⁵⁾			±128	mA
	Continuous current through V_{CC} or GND			±100	mA
θ_{JA}	Package thermal impedance ⁽⁶⁾	DGG package		70	°C/W
T_{stg}	Storage temperature range		-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
 (2) All voltages are with respect to ground unless otherwise specified.
 (3) The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 (4) V_I and V_O are used to denote specific conditions for $V_{I/O}$.
 (5) I_I and I_O are used to denote specific conditions for $I_{I/O}$.
 (6) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions⁽¹⁾

			MIN	MAX	UNIT
V _{CC}	Supply voltage		2.3	3.6	V
V _{IH}	High-level control input voltage	V _{CC} = 2.3 V to 2.7 V	1.7	5.5	V
		V _{CC} = 2.7 V to 3.6 V	2	5.5	
V _{IL}	Low-level control input voltage	V _{CC} = 2.3 V to 2.7 V	0	0.7	V
		V _{CC} = 2.7 V to 3.6 V	0	0.8	
V _{I/O}	Data input/output voltage		0	5.5	V
T _A	Operating free-air temperature		–40	125	°C

(1) All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

Electrical Characteristics⁽¹⁾

PARAMETER		TEST CONDITIONS	T _A = –40°C TO 125°C			UNIT
			MIN	TYP ⁽²⁾	MAX	
V _{IK}		V _{CC} = 3 V, I _I = –18 mA			–1.2	V
V _{OH}		See Figure 3 and Figure 4				
I _{IN}	Control inputs	V _{CC} = 3.6 V, V _{IN} = 3.6 V to 5.5 V or GND			±10	μA
I _I		V _{CC} = 3.6 V, Switch ON, V _{IN} = V _{CC} or GND	V _I = V _{CC} – 0.7 V to 5.5 V		±20	μA
			V _I = 0.7 V to V _{CC} – 0.7 V		–40	
			V _I = 0 to 0.7 V		±5	
I _{OZ} ⁽³⁾		V _{CC} = 3.6 V, V _O = 0 to 5.5 V, V _I = 0, Switch OFF, V _{IN} = V _{CC} or GND			±10	μA
I _{off}		V _{CC} = 0, V _O = 0 to 5.5 V, V _I = 0,			10	μA
I _{CC}		V _{CC} = 3.6 V, I _{I/O} = 0, Switch ON or OFF, V _{IN} = V _{CC} or GND	V _I = V _{CC} or GND		40	μA
			V _I = 5.5 V		40	
ΔI _{CC} ⁽⁴⁾	Control inputs	V _{CC} = 3 V to 3.6 V, One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND			300	μA
C _{in}	Control inputs	V _{CC} = 3.3 V, V _{IN} = V _{CC} or GND		4		pF
C _{io(OFF)}		V _{CC} = 3.3 V, V _{I/O} = 5.5 V, 3.3 V, or GND, Switch OFF, V _{IN} = V _{CC} or GND		5		pF
C _{io(ON)}		V _{CC} = 3.3 V, Switch ON, V _{IN} = V _{CC} or GND	V _{I/O} = 5.5 V or 3.3 V		5	pF
			V _{I/O} = GND		13	
r _{on} ⁽⁵⁾		V _{CC} = 2.3 V, TYP at V _{CC} = 2.5 V, V _I = 0	I _O = 24 mA		5	Ω
			I _O = 16 mA		5	
		V _{CC} = 3 V, V _I = 0	I _O = 24 mA		5	
			I _O = 16 mA		5	

(1) V_{IN} and I_{IN} refer to control inputs. V_I, V_O, I_I, and I_O refer to data pins.

(2) All typical values are at V_{CC} = 3.3 V (unless otherwise noted), T_A = 25°C.

(3) For I/O ports, the parameter I_{OZ} includes the input leakage current.

(4) This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

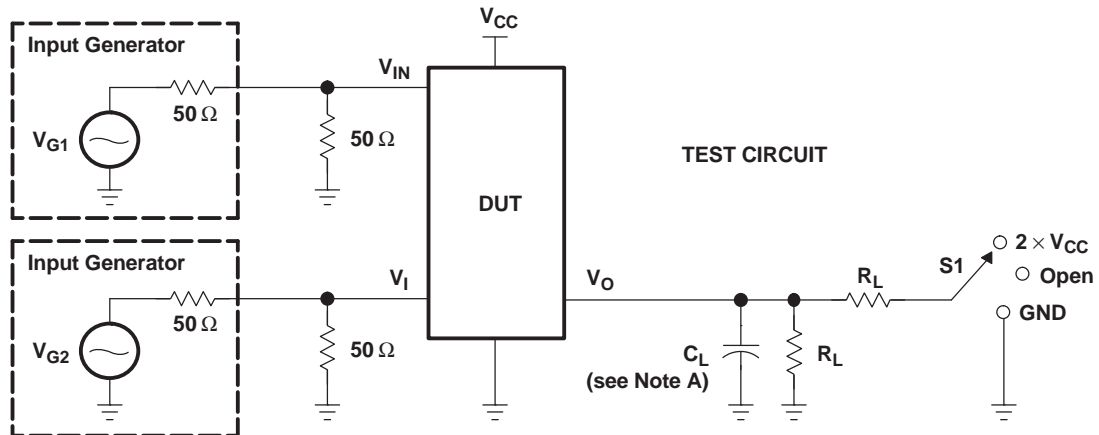
(5) Measured by the voltage drop between A and B terminals at the indicated current through the switch. ON-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

Switching Characteristics

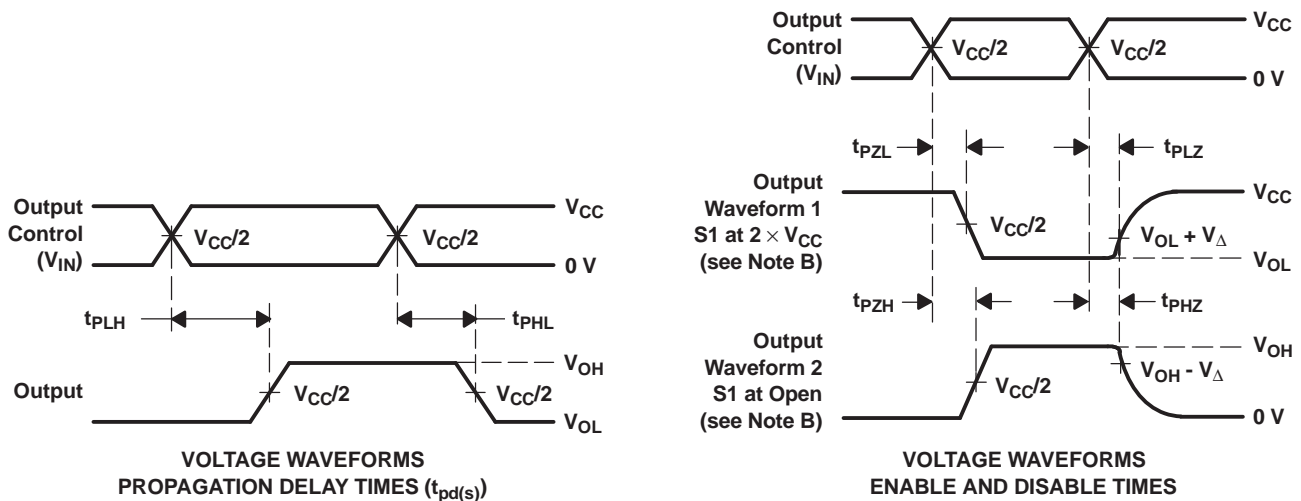
for $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$ (see [Figure 2](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
t_{en}	\overline{OE}	A or B	1	14	1	12	ns
t_{dis}	\overline{OE}	A or B	1	9.5	1	10.5	ns

PARAMETER MEASUREMENT INFORMATION



TEST	V _{CC}	S1	R _L	V _I	C _L	V _Δ
t _{pd(s)}	2.5 V ± 0.2 V	Open	500 Ω	3.6 V or GND	30 pF	
	3.3 V ± 0.3 V	Open	500 Ω	5.5 V or GND	50 pF	
t _{PLZ} /t _{PZL}	2.5 V ± 0.2 V	2 × V _{CC}	500 Ω	GND	30 pF	0.15 V
	3.3 V ± 0.3 V	2 × V _{CC}	500 Ω	GND	50 pF	0.3 V
t _{PHZ} /t _{PZH}	2.5 V ± 0.2 V	Open	500 Ω	3.6 V	30 pF	0.15 V
	3.3 V ± 0.3 V	Open	500 Ω	5.5 V	50 pF	0.3 V



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
 - The outputs are measured one at a time, with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis}.
 - t_{PZL} and t_{PZH} are the same as t_{en}.
 - t_{PLH} and t_{PHL} are the same as t_{pd(s)}. The t_{pd} propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).
 - All parameters and waveforms are not applicable to all devices.

Figure 2. Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

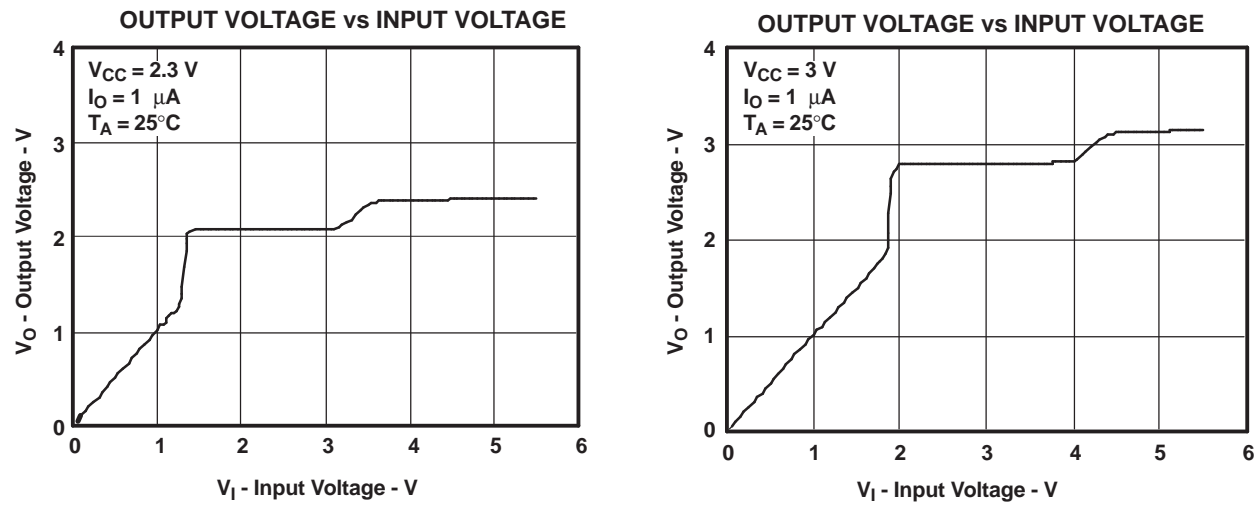


Figure 3. Data Output Voltage vs Data Input Voltage

TYPICAL CHARACTERISTICS

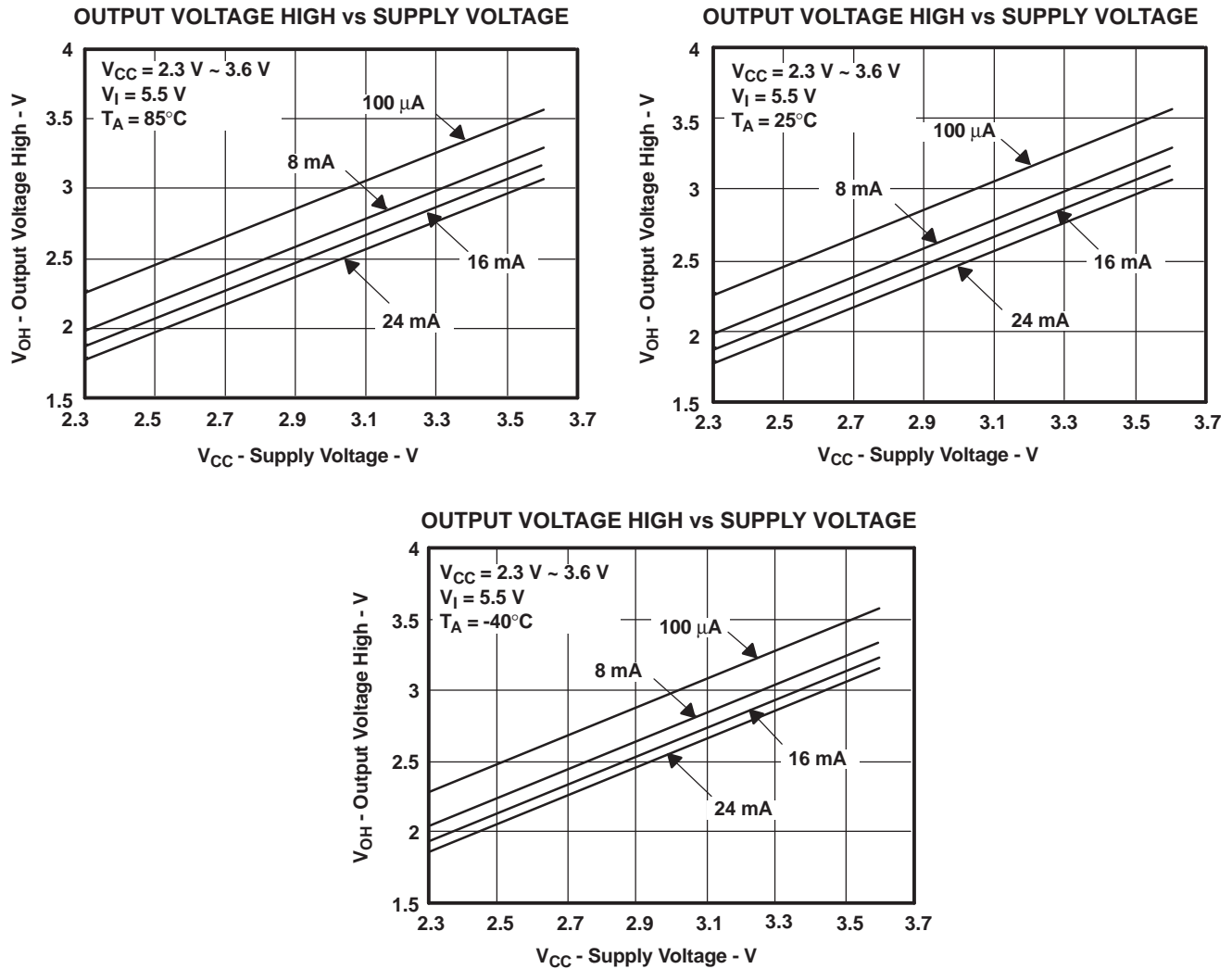


Figure 4. V_{OH} Values

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
CCB3T16210QDGGRQ1	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 125	CB3T16210Q	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

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Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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OTHER QUALIFIED VERSIONS OF SN74CB3T16210-Q1 :

- Catalog: [SN74CB3T16210](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CCB3T16210QDGGRQ1	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CCB3T16210QDGGGRQ1	TSSOP	DGG	48	2000	367.0	367.0	45.0

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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